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FOR IMMEDIATE RELEASE

Press Release

YINCAE'S New Highly Conductive Thermal Underfill: SMT 158D

(Albany, NY) 05/11/2018 — YINCAE Advanced Materials is proud to introduce SMT 158D, the world's first (and only) diamond filled underfill!

SMT 158D was developed in response to the need for underfill materials with a higher thermal conductivity. The thermal conductivity of SMT 158D is 6W/mK, compared to the thermal conductivity of traditional silicon dioxide filled underfill which has a thermal conductivity of less than 1W/mK. Increased thermal conductivity improves reliability in a variety of devices, and is ideal for packages where heat build up is a concern.

SMT 158D is a diamond filled, rapid curing, fast flowing and easily reworked liquid epoxy that can be used for flip chips, chip scale packages, ball grid array devices, package and land grid array applications. It is also suitable for bare chip protection in a variety of advanced packages such as memory cards, chip carriers, hybrid circuits and multi-chip modules.

SMT 158D has been designed for a high production environment where process speed, thermal issues, and reliability are the key concerns. This material is easily dispensed, minimizes induced stresses and provides outstanding reliability performance (e.g., temperature cycling performance) and excellent mechanical resistance.

For more information on YINCAE's SMT 158D underfill, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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